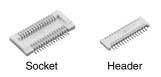
Panasonic ideas for life





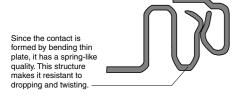
Compliance with RoHS Directive http://www.nais-e.com/

FEATURES

- 1. Low profile mating height of 1.2 mm with 0.5 mm pitch, was obtained. It contributes to device compactness.
- 2. Strong resistance to adverse environments! Utilizes

TDUGH CONTRLT construction for high contact reliability.

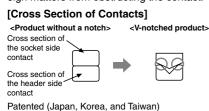
1) Contacts are highly resistant to shock caused by dropping and employ our original bellows contact construction.



2) V notch construction used for excellent resistance against foreign matters.

V-notch

By making contact with the edges and thus increasing the contact pressure, this product can eliminate flux and other foreign matters more effectively than conventional products, which also helps to prevent foreign matters from obstructing the contact.



NARROW-PITCH CONNECTORS FOR BOARD-TO-BOARD CONNECTION

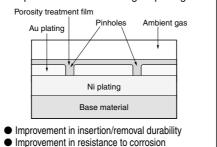
3) Use of Ni barrier construction is standard. Highly effective against solder creeping.

The exposed nickel-plated portion of the gold-plated contact prevents solder creep despite the ultra low profile of the contact. [Contact] Header side contact Ni barrier Cu Ni Au Exposed Ni part Cross section of header side post

4) Porosity treatment applied for improved resistance against corrosion.

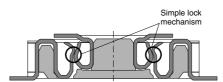
Porosity treatment

This treatment consists in coating the surface with a very thin film to seal pinholes in the gold plating. We have developed this porosity treatment technology, which ensures contact reliability for thin gold plating comparable to that of thick gold plating.



3. Simple lock structure employed to further increase connection reliability

• Improvement in contact reliability for digital signals



4. Effective mating length 0.3 mm



NARROW PITCH (0.5mm) CONNECTORS P5 SERIES — P5KL—

5. Compliance with RoHS' Directive Environmentally friendly, the connectors' comply with Europe's RoHS' Directive. Cadmium, lead, mercury, hexavalent, chromium, PBB and PBDE are not used.

APPLICATIONS

Compact portable devices "Cellular phones, DVC, Digital cameras, etc"

Ideal for Board-to-FPC connections

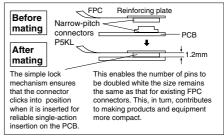
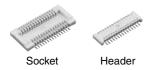


TABLE OF PRODUCT TYPES

P5KL (0.5 mm pitch): Without retention fitting



 \Rightarrow : Available for sale

Mated height		1.2mm
	10	☆
ts	12	☆
Number of contacts	20	☆
	24	☆
	30	☆
	34	☆
	40	☆
	50	☆
	60	☆

Notes: 1. The standard type comes with positioning bosses.

Connectors with positioning boss are available for on-demand production.

2. Please consult us regarding numbers of contacts other than those given above.

ORDERING INFORMATION

AXK	7 G
5L: Narrow Pitch Connector P5KL (0.5 mm pitch) Socket 6L: Narrow Pitch Connector P5KL (0.5 mm pitch) Header	
Number of contacts (2 digits)	
Mated height <socket> 3: For mated height 1.2 mm <header> 3: For mated height 1.2 mm</header></socket>	
Functions 3: With positioning bosses 4: Without positioning bosses	
Surface treatment (Contact portion / Terminal portion) 7: Ni plating on base, Au plating on surface (for Ni barrier product availab	ole)
Packing G: 3,000 pieces embossed tape and plastic reel \times 2 (for Ni barrier production)	ct available)

PRODUCT TYPES

		Pa	rt No.	Packing quantity		
Mated height No. of	No. of contacts	Socket Header		Inner carton	Outer carton	
		TOUGH CONTRET	TOUGH CONTACT	(1-reel)	Outer carton	
10 12 20 24 1.2 mm 30 34 40 50 60	10	AXK5L10347G	AXK6L10347G			
	12	AXK5L12347G	AXK6L12347G	L12347G		
	20	AXK5L20347G	AXK6L20347G			
	24 AXK5L24347G	AXK6L24347G				
	30	AXK5L30347G	AXK6L30347G	3,000 pieces	6,000 pieces (2-reel)	
	34	AXK5L34347G	AXK6L34347G			
	40	AXK5L40347G	AXK6L40347G			
	50 AXK5L50347G	AXK6L50347G				
	60	AXK5L60347G	AXK6L60347G			

Notes) 1. Regarding ordering units: During production, Please make orders in 1-reel units. Samples for mounting confirmation: Please consult us. Samples: Small lot orders are possible. Please consult us.

2. The standard type comes without positioning bosses. Connectors with positioning bosses are available for on-demand production.

SPECIFICATIONS

1. Characteristics

	Item	Specifications	Conditions		
Rated current		0.5A/contact (Max. 10 A at total contacts)			
Electrical	Rated voltage	60V AC/DC			
	Breakdown voltage	150V AC for 1 minute	Detection current: 1mA		
characteristics	Insulation resistance	Min. 1,000MΩ (initial)	Using 500V DC megger		
	Contact resistance	Max. 90mΩ	Measured based on the HP4338B measurement method of JIS C 5402		
	Composite insertion force	Max. 0.981N {100gf}/contacts × contacts (initial)			
Mechanical	Composite removal force	Min. 0.0588N {6gf}/contacts × contacts			
characteristics	Holding force of terminal securing section	Min. 0.981N {100gf}/contact	Measures the maximum load in the post axial direction until removal		
Environmental characteristics	Ambient temperature	−55°C to +85°C	No freezing at low temperatures		
		Max. peak temperature of 260°C	Infrared reflow soldering		
	Soldering heat resistance	300°C within 5 seconds 350°C within 3 seconds	Soldering iron		
	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Sequence 1. –55.\(\frac{9}{3}\) °C, 30 minutes 2. \(\simeq\), Max. 5 minutes 3. 85\(\frac{9}{3}\) °C, 30 minutes 4. \(\simeq\), Max. 5 minutes		
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Bath temperature 40±2°C, humidity 90 to 95% R.H.		
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100M Ω , contact resistance max. 90m Ω	Bath temperature 35±2°C, saltwarter concentration 5±1%		
	H ₂ S resistance (header and socket mated)	48 hours, contact resistance max. $90m\Omega$	Bath temperature 40±2°C, gas concentration 3±1 ppm, humidity 75 to 80% R.H.		
ifetime characteristics	Insertion and removal life	50 times	Repeated insertion and removal speed of max. 200 times/hours		
Unit weight		20 contacts; Socket: 0.05g; Header: 0.02g			

2. Material and surface treatment

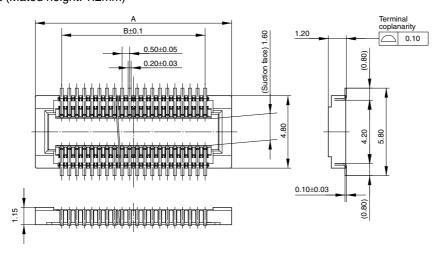
Part name	Material	Surface treatment		
Molded portion	Heat-resistant resin (UL94V-0), Ivory white	-		
Contact/Post	Copper alloy	Contact portion: Ni plating on base, Au plating on surface Terminal portion: Ni plating on base, Au plating on surface (Except for thick of terminal) However, the area adjacent to the terminal on Ni barrier models is exposed to Ni on base.		

For this type of connector, 9th digit of the part no. changes from 4 to 3. e.g. 10 contacts for sockets: AXK5L10337G

DIMENSIONS

mm General tolerance: ±0.2

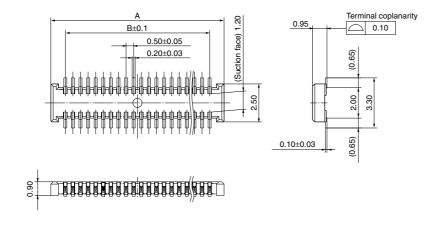
• Socket (Mated height: 1.2mm)



Dimension table (mm)

No. of contacts	Α	В
10	5.50	2.00
12	6.00	2.50
20	8.00	4.50
24	9.00	5.50
30	10.50	7.00
34	11.50	8.00
40	13.00	9.50
50	15.50	12.00
60	18.00	14.50

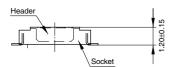
• Header (Mated height: 1.2mm)



Dimension table (mm)

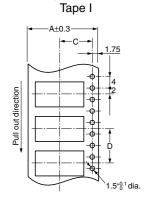
No. of contacts	Α	В	
10	3.90	2.00	
12	4.40	2.50	
20	6.40	4.50	
24	7.40	5.50	
30	8.90	7.00	
34	9.90	8.00	
40	11.40	9.50	
50	13.90	12.00	
60	16.40	14.50	

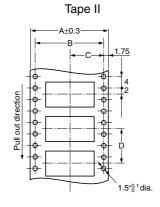
• Socket and header are mated

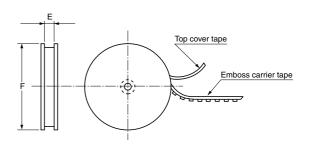


EMBOSSED TAPE DIMENSIONS (unit:mm, Common for respective contact type, socket and header)

- Tape dimensions (Conforming to JIS C 0806-1990. However, some tapes have mounting hole pitches that do not comply with the standard.)
- Plastic reel dimensions (Conforming to EIAJ ET-7200B)/
 Paper reel dimensions (Conforming to JIS C 0806-1990)





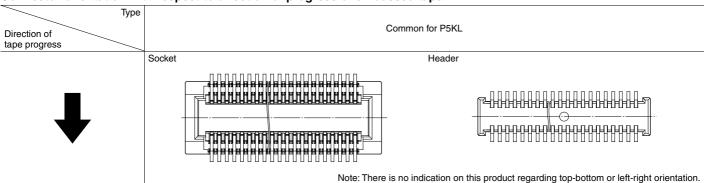


Dimension table (mm)

Suffix: G (1 reel, 3,000 pieces embossed tape: Plastic reel package)

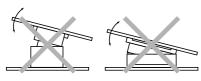
Mated height	No. of contacts	Type of taping	Α	В	С	D	E	F	Quantity per reel
Socket and header are common: 1.2mm	10 to 18	Tape I	16.0	_	7.5	8.0	17.4±1	380 dia.	3,000 pcs.
	20 to 50	Tape I	24.0	_	11.5	8.0	25.4±1	380 dia.	3,000 pcs.
	60	Tape II	32.0	28.4	14.2	8.0	33.4±1	380 dia.	3,000 pcs.

Connector orientation with respect to direction of progress of embossed tape

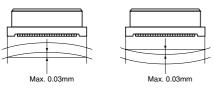


NOTES

1. As shown below, excess force during insertion may result in damage to the connector or removal of the solder. Please be careful. Also, to prevent connector damage plese confirm the correct position before mating connectors.



2. Keep the PC board warp no more than 0.03 mm in relation to the overall length of the connector.

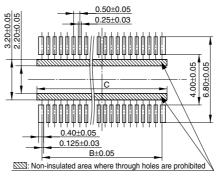


3. PC Boards and Recommended Metal Mask Patterns

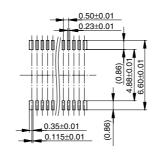
Connectors are mounted with high density, with a pitch interval of 0.4 to 0.5 mm. It is therefore necessary to make sure that the right levels of solder are used, in order to reduce solder bridge and other issues. The figures to the right are recommended metal mask patterns. Please use them as a reference.

Socket

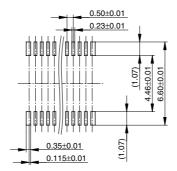
Reconnended PC board pattern (TOP VIEW)



Recommended metal mask pattern Metal mask thickness: 150 µm (Terminal portion opening area ratio: 57%)



Recommended metal mask pattern Metal mask thickness: 120 µm (Terminal portion opening area ratio: 70%)

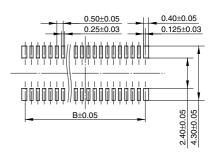


Notes: 1. See the dimension table on page 59 for more information on the B dimension of the socket and header.

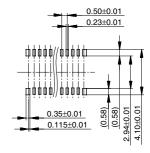
The socket C dimension is the B dimension in the dimensions table with 0.8 added.

Header

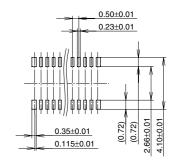
Reconnended PC board pattern (TOP VIEW)



Recommended metal mask pattern Metal mask thickness: 150 µm (Terminal portion opening area ratio: 56%)



Recommended metal mask pattern Metal mask thickness: 120 µm (Terminal portion opening area ratio: 70%)



Regarding general notes, please refer to page 12.

For other details, please verify with the product specification sheets.